

Title (en)

METHOD AND INSERT MATERIAL FOR BLOCKING FLOW OF SOLDER MATERIAL INTO A VOID

Title (de)

VERFAHREN UND EINSETZMATERIAL ZUR BLOCKIERUNG DES FLUSSES VON LOTMATERIAL IN EINEN HOHLRAUM

Title (fr)

PROCÉDÉ ET MATÉRIAU D'INSERT PERMETTANT DE BLOQUER L'ÉCOULEMENT D'UN MATÉRIAU DE SOUDURE DANS UN VIDE

Publication

EP 3360637 A1 20180815 (EN)

Application

EP 18154449 A 20180131

Priority

CN 201710069523 A 20170208

Abstract (en)

An insert material (18) for blocking flow of solder material into a void (12) of a component (10) during soldering operation is disclosed, which comprises micro-sized metal oxide particles; nano-sized metal oxide particles; and binder. A method for blocking flow of solder material into a void (12) of a component (10) during soldering operation is also disclosed, which comprises preparing insert material (18) in form of slurry comprising micro-sized metal oxide particles, nano-sized metal oxide particles, and binder; charging the insert material (18) into the void (12); drying the insert material (18) in the void (12) which seals the void (12); performing soldering operation; and removing the insert material (18) after soldering operation.

IPC 8 full level

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Citation (search report)

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